

Title (en)

Process for copper electroless plating on iron or iron alloys surfaces

Title (de)

Verfahren zur stromlosen Abscheidung von Kupferüberzügen auf Eisen- und Eisenlegierungsflächen

Title (fr)

Procédé de dépôt chimique de cuivre sur des surfaces en fer ou alliage de fer

Publication

EP 0711848 B1 20030212 (DE)

Application

EP 95116255 A 19951016

Priority

DE 4440299 A 19941111

Abstract (en)

[origin: EP0711848A1] Electroless copper deposition on iron (alloy) surfaces involves contacting the surfaces with a soln. contg. 5-30 g/l Cu and 0.2-5 g/l Mg, the Cu:Mg wt. ratio being esp. 5-35:1. Also claimed is a solid concentrate for making up and replenishing the soln. used in the above process.

IPC 1-7

C23C 18/38

IPC 8 full level

C23C 18/38 (2006.01)

CPC (source: EP US)

C23C 18/38 (2013.01 - EP US)

Citation (examination)

- CLIFFORD A. HAMPEL: "Encyclopedia of Electrochemistry", 1964, ROBERT E. KRIEGER PUBLISHING COMPANY, HUNTINGTON, N.Y.
- LAWRENCE J. DURNEY: "Electroplating Engineering Handbook", 1984, VAN NOSTRAND REINHOLD COMPANY LTD, NEW YORK, N.Y.

Cited by

WO2012022660A1; WO02053801A3

Designated contracting state (EPC)

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DOCDB simple family (publication)

EP 0711848 A1 19960515; EP 0711848 B1 20030212; AT E232563 T1 20030215; DE 4440299 A1 19960515; DE 59510554 D1 20030320; ES 2192567 T3 20031016; US 5776231 A 19980707; US 6261644 B1 20010717

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EP 95116255 A 19951016; AT 95116255 T 19951016; DE 4440299 A 19941111; DE 59510554 T 19951016; ES 95116255 T 19951016; US 55428895 A 19951106; US 80202997 A 19970218